

Preliminary Information

September 1990

Description

The μPD72064 FDC is NEC's highly integrated solution for PC/AT-type floppy-disk controller designs. Like its predecessor, the μPD72068, the μPD72064 maintains complete microcode compatibility with the industry standard μPD765 and contains the latest enhancements required for multitasking applications. Additionally, the μPD72064 provides the complete host-interface register set for PC/AT support.

The μPD72064 incorporates a high-performance digital PLL that is impervious to harmonic lock-on, a characteristic of analog counterparts. Being digital, the PLL requires no adjustments and supports all standard data rates.

The μPD72064 has on-chip clock generation, selectable write precompensation, and all the circuitry necessary for interfacing directly to four floppy-disk drives.

Features

- Software compatible with μPD765A/B and μPD72065/65B
- Pinout compatible with WD37C65; uses 32-MHz and 19.2-MHz crystals
- IBM PC/AT compatible recording format
- On-chip peripheral circuits
 - High-performance DPLL data separator
 - Dual-circuit system clock generator
 - Host interface register for IBM PC/AT
 - Write precompensator (programmable preshift)
- FDD interface
 - High-current drivers (48-mA sink)
 - Schmitt receivers
- Data transfer rates
 - MFM: 500, 300, 250 kb/s
 - FM: 250, 150, 125 kb/s
- Power saving standby mode ($I_{DD1} = 100 \mu A$ maximum)
- One crystal for standard data rates: MFM 250, 500 kb/s
- Switches maximum step pulses (77/255) when recalibrating
- Controls up to four FDDs
- Dual-speed spindle motor control
- DMA or non-DMA data transfer from main system

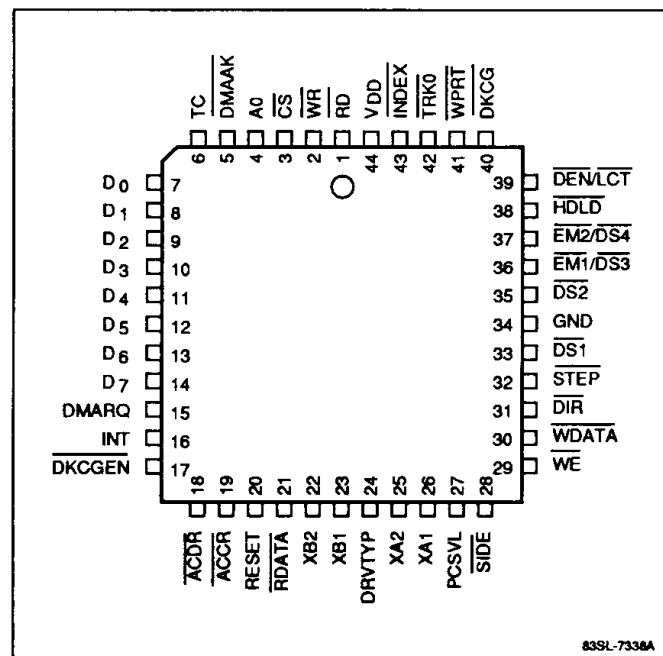
- Multisector and multitrack transfer
- Programmable step rate and head load/unload time
- CMOS
- Single + 5-volt power supply

Ordering Information

Part Number	Package
μPD72064LM	44-pin PLCC
μPD72064GC-3B6	52-pin plastic QFP

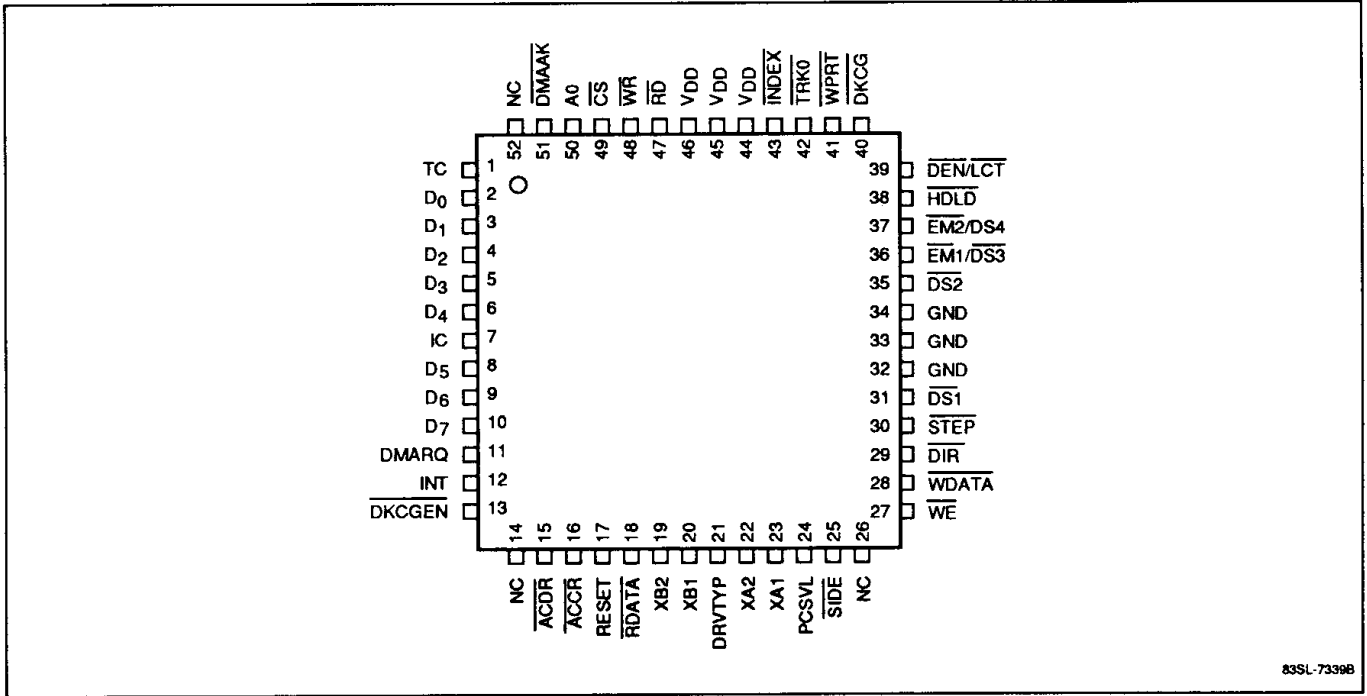
Pin Configurations

44-Pin PLCC



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52-Pin Plastic QFP



83SL-7339B

Pin Identification

Symbol	I/O	Signal Function
A0	In	Address 0. Selects μPD72064 registers. A0 Registers 0 Status, auxiliary command 1 Data
ACCR	In	Selects control register and digital input register when ACCR = 0.
ACDR	In	Selects digital out register when ACDR = 0.
CS	In	Chip Select. Allows RD and WR signals to be enabled.
D ₀ -D ₇	I/O	Data Bus. Bidirectional, three-state data bus.
DEN/LCT (3)	Out	Density/Low Current. Base or special mode: Indicates the read/write heads are positioned on cylinder 43 or later. Please refer to table 8 for operation in PC/AT mode.
DIR (3)	Out	Specifies the seek direction. DIR Seek Direction 0 Centripetal 1 Centrifugal
DKCG (3)	In	Indicates drive status. DKCG = 0 means the drive latch is left unlocked (a medium may be exchanged or inserted).
DKCGEN (1)	In	Enables disk change signal (DKCG).
DMAAK	In	DMA Acknowledge. Enables DMA cycle.

Symbol	I/O	Signal Function
DMARQ	Out	DMA Request. Requests data transfer in DMA mode.
DRV TYP	In	Allows a two-speed spindle motor to be used when DRV TYP = 1. Set this pin to 0 if the XB clock is not used.
DS1, DS2 (3)	Out	Selects a drive.
EM1/DS3, EM2/DS4 (3)	Out	PC/AT mode: Becomes EM1, EM2 to control the spindle motor. Base or special mode: Becomes DS3, DS4 to select a drive.
HDLD (3)	Out	Head Load. Places the read/write heads in the load state.
INDEX (2)	In	Indicates a read/write head is positioned at the physical start point of track on the medium.
INT	Out	Interrupt Request. Requests main system to process transferred data or execution results.
PCSVL	In	Sets the pre-shift value used when the transfer rate of 500/250 kb/s (MFM) is applied. PCSVL Pre-Shift Value 0 187 ns for cylinder 43 or later; 0 ns for cylinder 42 or earlier 1 125 ns

Pin Identification (cont)

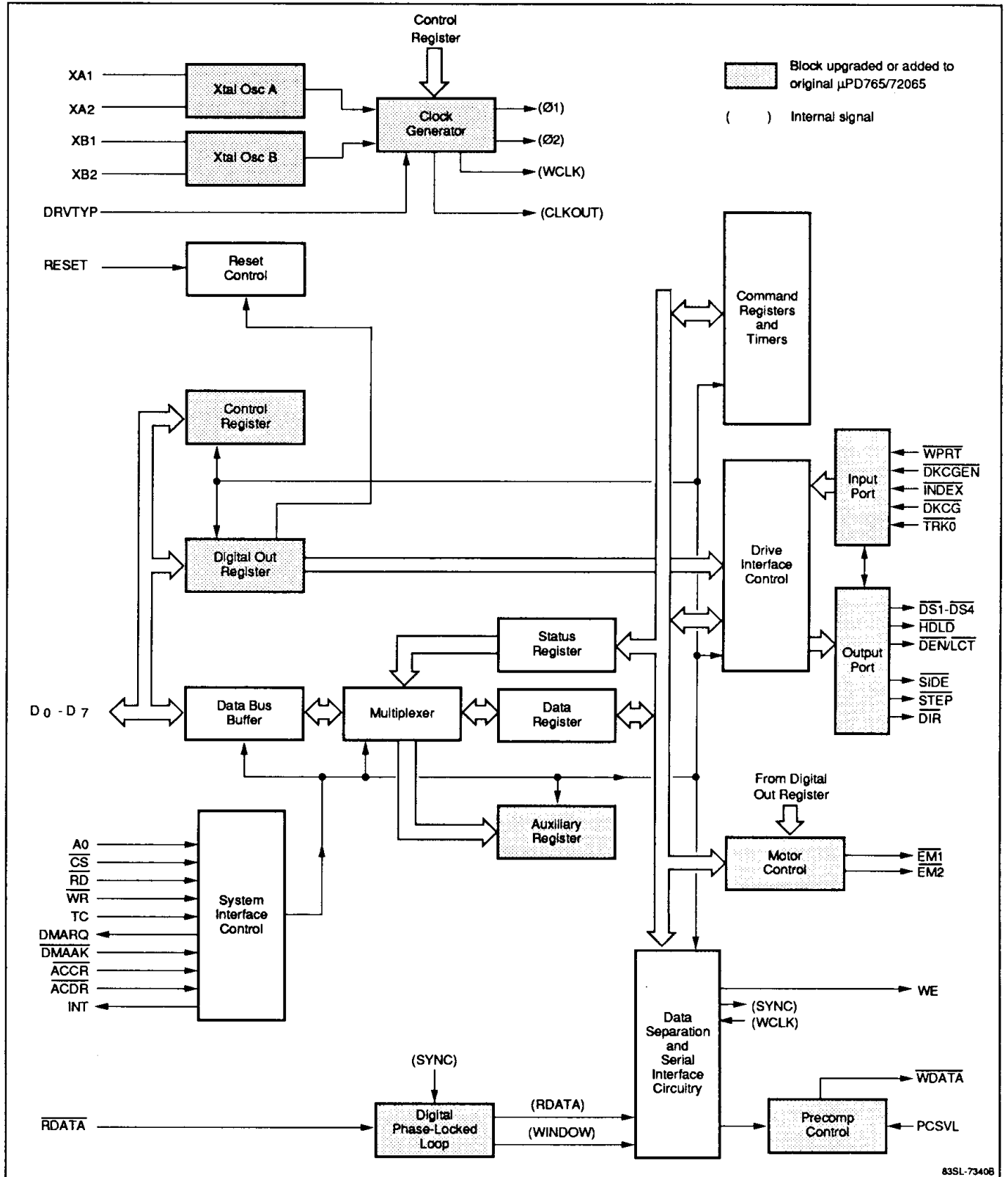
Symbol	I/O	Signal Function						
\overline{RD}	In	Read. Signal causes the main system to read data from the μPD72064 to the data bus.						
\overline{RDATA} (2)	In	Read data (consists of clock and data bits) from FDD.						
RESET	In	Places the μPD72064 in the idle state. All pins on the drive side are in the high-impedance state. On the main system side, INT and DMARQ pins are in the floating state, and D ₀ -D ₇ pins are in the input state.						
\overline{SIDE} (3)	Out	Selects read/write head 0 or 1 of the double-sided drive. <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>\overline{SIDE}</th> <th>Read/Write</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>Head 1</td> </tr> <tr> <td>1</td> <td>Head 0</td> </tr> </tbody> </table>	\overline{SIDE}	Read/Write	0	Head 1	1	Head 0
\overline{SIDE}	Read/Write							
0	Head 1							
1	Head 0							
STEP (3)	Out	Generates step pulses for the seek movement						
TC	In	Terminal Count. Indicates data transfer is ended.						
$\overline{TRK0}$ (2)	In	Indicates read/write heads are positioned at cylinder 0.						
\overline{WDATA} (3)	Out	Write data (clock and data bits) to FDD.						
\overline{WE} (3)	Out	Indicates write to the drive.						
\overline{WPRT} (2)	In	Indicates medium is write-protected.						

Symbol	I/O	Signal Function
\overline{WR}	In	Write. Control signal that allows the main system to write data bus data into the μPD72064.
XA1, XA2	In	Crystal A. For internal oscillator frequency control, a crystal resonator is connected to XA1 and XA2. For external clock input at XA1, XA2 is open. Frequency = 32 MHz
XB1, XB2	In	Crystal B. For internal oscillator frequency control, a crystal resonator is connected to XB1 and XB2. For external clock input at XB1, XB2 is open. Frequency = 19.2 MHz
IC		Internal Connection
NC	—	No Connection
GND	—	Ground
V _{DD}	In	+5-volt power supply

Notes:

- (1) Internal pullup.
- (2) Schmitt trigger input.
- (3) High-current driver (48-mA sink current).

μPD72064 Block Diagram



83SL-73408

REGISTERS

Table 1 describes the six 8-bit registers in the 72064 Floppy-Disk Controller (FDC) that interface with the main system.

Table 1. Registers

Name	Description
Data register	Temporarily stores information to be transferred between the FDC and the main system; for example, a command code, a parameter, data, or a result status.
Status register	Indicates FDC status; register can be read by the main system at any time.
Auxiliary command register	Temporarily stores a command for the FDC.
Digital out register	Selects mode (PC/AT or special), drive, motor control, software reset, and INT/DMARQ control.
Control register	Sets data transfer rate.
Digital input register	Indicates drive status (\overline{DKCG}).

Register Selection

As shown in table 2, the logic state of input pins A_0 , \overline{CS} , \overline{ACDR} , and \overline{ACCR} selects a particular register. The state of input pins \overline{WR} and \overline{RD} selects register write or register read.

If the DMA acknowledge input (\overline{DMAAK}) is active, the data register will be selected regardless of the \overline{CS} and A_0 input states.

- (1) \overline{ACCR} or \overline{ACDR} input will be held inactive.
- (2) If both \overline{CS} and A_0 inputs are 0, the write of any code other than an auxiliary command code ($\overline{WR} = 0$) will be inhibited.

Table 2. Register Selection

Operation	\overline{WR}	\overline{RD}	A_0	\overline{CS}	\overline{ACDR}	\overline{ACCR}
Status register read	1	0	0	0	1	1
Auxiliary command register write	0	1	0			
Data register read	1	0	1			
Data register write	0	1	1			
Nonselection	x	x	x	1	1	1
Digital out register write	0	1	x	1	0	1
Control register write	0	1	x	1	1	0
Digital input register read	1	0	x	1	1	0

x = Don't care

Main Status Register

The main status register contains the status information of the FDC and may be accessed any time. Only the status register may be read and used to facilitate the transfer of data between the processor and the FDC.

The main status register bits are defined in table 3. Bits DIP and RQM indicate when data is ready and in which direction data will be transferred on the data bus. See figure 1.

Data Register

The data register stores data, commands, parameters, and FDD status information. Data bytes are read out of or written into the data register in order to program or obtain the results after a particular command.

Status registers ST0-ST3 (table 4) are stored in a stack with only one register at a time presented through the data register during the Result phase of a command.

Auxiliary Command Register

This register temporarily stores a command for the FDC. Auxiliary commands include Set Standby, Reset Standby, Software Reset, Start Clock, and Select Track Number.

Table 3. Main Status Register

Bit	Name	Function
D ₀	D ₀ B (FDD 0 Busy)	FDD 0 is in the seek mode. If any of the D _n B bits is set, FDC will not accept a read or write command.
D ₁	D ₁ B (FDD 1 Busy)	FDD 1 is in the seek mode. If any of the D _n B bits is set, FDC will not accept a read or write command.
D ₂	D ₂ B (FDD 2 Busy)	FDD 2 is in the seek mode. If any of the D _n B bits is set, FDC will not accept a read or write command.
D ₃	D ₃ B (FDD 3 Busy)	FDD 3 is in the seek mode. If any of the D _n B bits is set, FDC will not accept a read or write command.
D ₄	CB (FDC Busy)	A read or write command is in process. FDC will not accept any other command.
D ₅	EXM (Execution Mode)	This bit is set only during execution phase in non-DMA mode. When DB ₅ goes low, execution phase has ended and result phase has started. It operates only during non-DMA mode of operation.
D ₆	DIO (Data Input/Output)	Indicates direction of data transfer between FDC and data register. If DIO = 1, transfer is from data register to processor. If DIO = 0, transfer is from processor to data register.
D ₇	RQM (Request for Master)	Indicates data register is ready to send or receive data to or from the processor. Both bits DIO and RQM should be used to perform the handshaking functions of "ready" and "direction" to the processor.

Table 4. Status Registers ST0-ST3

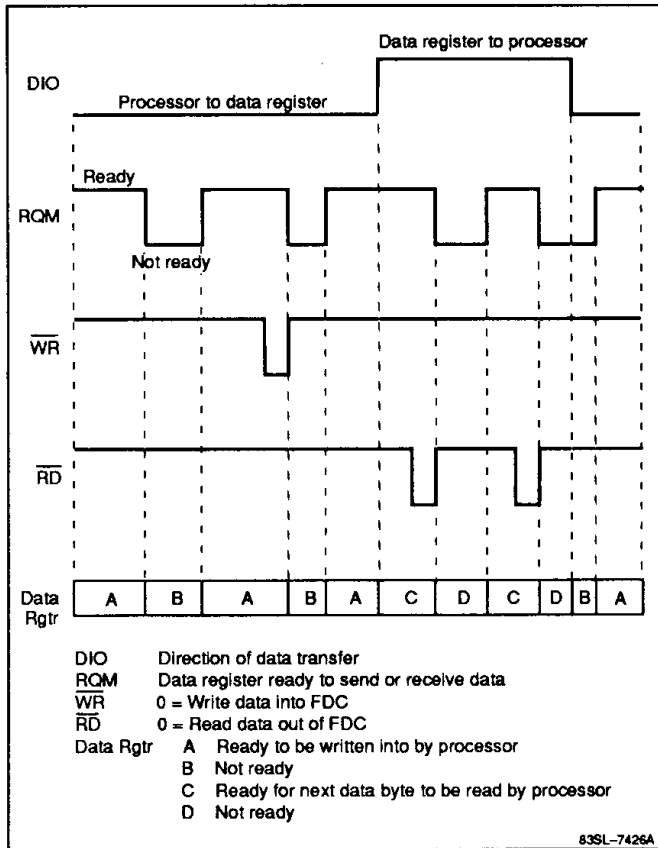
Bit	Name	Function
Status Register ST0		
D ₇ , D ₆	IC (Interrupt Code)	<p>D₇ = 0 and D₆ = 0. Normal termination of command (INT). Command was completed and properly executed.</p> <p>D₇ = 0 and D₆ = 1. Abnormal termination of command (AT). Execution of command was started but was not successfully completed.</p> <p>D₇ = 1 and D₆ = 0. Invalid command issue (IC). Command that was issued was never started.</p> <p>D₇ = 1 and D₆ = 1. Abnormal termination because during command execution the ready signal from the FDD changed state.</p>
D ₅	SE (Seek End)	When the FDC completes the Seek command, this flag is set to 1.
D ₄	EC (Equipment Check)	If a fault signal is received from the FDD, or if the track 0 signal fails to occur after 77 step pulses (Recalibrate command), then this flag is set.
D ₃	NR (Not Ready)	When the FDD is in the not-ready state and Read or Write command is issued, this flag is set. If a Read or Write command is issued to head 1 of a single-sided drive, then this flag is set.
D ₂	HD (Head Address)	This flag indicates the state of the head at interrupts.
D ₁	US ₁ (Unit Select1)	This flag indicates a drive unit number at interrupt.
D ₀	US ₀ (Unit Select 0)	This flag indicates a drive unit number at interrupt.

CRC Cyclic Redundancy Check
 IDR Internal Data Register
 C Current/selected cylinder (track) 0 through 76 of the medium.

Table 4. Status Registers ST0-ST3 (cont)

Bit	Name	Function
Status Register ST1		
D ₇	EN (End of Cylinder)	When the FDC tries to access a sector beyond the final sector of a cylinder, this flag is set.
D ₆		Not used. This bit is always 0.
D ₅	DE (Data Error)	When the FDC detects CRC(1) error in either the ID field or the data field, this flag is set.
D ₄	OR (Overrun)	If the FDC is not serviced by the host system during data transfers within a certain time interval, this flag is set.
D ₃		Not used. This bit is always 0.
D ₂	ND (No Data)	During execution of Read Data, Read Deleted Data, Write Data, Write Deleted Data, or Scan command, if the FDC cannot find the sector specified in the IDR(2) register, this flag is set. During execution of the Read ID command, if the FDC cannot read the ID field without an error, this flag is set. During execution of the Read Diagnostic command, if the starting sector cannot be found, this flag is set.
D ₁	NW (Not Writable)	During execution of Write Data, Write Deleted Data, or Write ID command, if the FDC detects a write protect signal from the FDD, this flag is set.
D ₀	MA (Missing Address Mark)	This bit is set if the FDC does not detect the IDAM before two index pulses. It is also set if the FDC cannot find the DAM or DDAM after the IDAM is found. The MD bit of ST2 is also set at this time.
Status Register ST2		
D ₇		Not used. This bit is always 0.
D ₆	CM (Control Mark)	During execution of the Read Data or Scan command, if the FDC encounters a sector containing a deleted data address mark, this flag is set. It is also set if DAM is found during Read Deleted Data.
D ₅	DD (Data Error in Data Field)	If the FDC detects a CRC error in the data field, this flag is set.
D ₄	WC (Wrong Cylinder)	This bit is related to the ND bit, and when the contents of C(3) on the medium is different from that stored in the IDR, this flag is set.
D ₃	SH (Scan Equal Hit)	During execution of the Scan command, if the condition of "equal" is satisfied, this flag is set.
D ₂	SN (Scan Not Satisfied)	During execution of the Scan command, if the FDC cannot find a sector on the cylinder that meets the condition, this flag is set.
D ₁	BC (Bad Cylinder)	This bit is related to the ND bit, and when the contents of C on the medium is different from that stored in the IDR and the contents of C is FFH, this flag is set.
D ₀	MD (Missing Address Mark in Data Field)	When data is read from the medium, if the FDC cannot find a data address mark or deleted data address mark, this flag is set.
Status Register ST3		
D ₇	FT (Fault)	Indicates status of fault signal from the FDD.
D ₆	WP (Write Protected)	Indicates status of write protected signal from the FDD.
D ₅	RY (Ready)	Indicates status of ready signal from the FDD.
D ₄	T0 (Track 0)	Indicates status of track 0 signal from the FDD.
D ₃	TS (Two-Side)	Indicate status of two-side signal from the FDD.
D ₂	HD (Head Address)	Indicates status of side select signal from the FDD.
D ₁	US ₁ (Unit Select 1)	Indicates status of unit select 1 signal to the FDD.
D ₀	US ₀ (Unit Select 0)	Indicates status of unit select 0 signal to the FDD.

Figure 1. Main Status Register; Bits DIO and RQM



Digital Out Register

This register (table 5) provides PC/AT or special mode selection, drive selection, motor control, software reset, and INT/DMARQ.

Control Register

The control register (table 6) sets the data transfer rate.

Digital Input Register

The function of the Digital Input register (table 7) is to provide the Disk Change (DKCG) status to the FDC.

Table 5. Digital Out Register

Bit	Name	Function
D7	MDSEL	Mode select: 1 Special mode 0 PC/AT mode
D6		Not used
D5	ENABLE MOTOR2	Motor control signal for drive 2. Setting D5 to 1 in PC/AT mode activates the EM2 pin.
D4	ENABLE MOTOR1	Motor control signal for drive 1. Setting D4 to 1 in PC/AT mode activates the EM1 pin.
D3	ENABLE INT/DMARQ	Enables the INT/DMARQ signal from the FDC. When D3 is 0, the INT and DMARQ pins will be in the high-impedance state, and the DMAAK and TC signals will be disregarded.
D2	RESET FDC	Reset signal for the FDC: 0 Set the reset state. 1 Clear the reset state.
D1		Not used.
D0	SELECT	Selects drive signal in the PC/AT mode: 0 DS1 is active if EM1 is active. 1 DS2 is active if EM2 is active.

Table 6. Control Register

Bit	Name	Function
CR7-CR2		Not used. (Set these bits to 0.)
CR1, CR0	DATA RATE	Sets the data transfer rate. (See table 8.)

Table 7. Digital Input Register

Bit	Name	Function
D7	DKCG	Indicates the drive status. 0 The latch of the drive is left open or a medium may be changed.
D6-D0		Not used. (High-impedance state when read.)

OUTPUTS

Data Transfer Rate

Regardless of mode, the data transfer rate is set by bits CR1 and CR0 of the control register and by the logic state of the DRV Typ input pin. See table 8.

Write Precompensation

Regardless of mode, the pre-shift value for MFM-type modulation is set by the logic state of the PCSVL pin according to the data transfer rate. See table 9.

Drive Select

In the base or special mode of the μPD72064, drive select is set by bits US0 and US1. In the PC/AT mode, it is set by bits D0, D4, and D5 of the digital out register; see table 10.

Table 8. Setting Data Transfer Rate

Data Transfer Rate, kb/s MFM (FM)	Control Register		DRV Typ Pin Input	DEN Pin Output
	CR1	CR0		
500 (250)	0	0	0	1
250 (125)	*0	1	0	0
	1	1	0	0
	1	0	0	0
300 (150)	*0	1	1	0

* State at the time the FDC is reset.

Table 9. Setting Pre-Shift Value

Data Transfer Rate, MFM (kb/s)	PCSVL Pin Input	Pre-Shift Value (ns)	Number of Tracks
500, 250	1	125	N/A
	0	187	≥ 43
		0	≤ 42
300	N/A	208	N/A

N/A = Not applicable

Table 10. Setting Drive Select in PC/AT Mode

D0 (SELECT)	Digital Out Register		Drive Select Output	
	D4 (ENABLE MOTOR1)	D5 (ENABLE MOTOR2)	DS1	DS2
0	1	x	0	1
1	x	1	1	0

SYSTEM CLOCK

Table 11 lists the connections from an external crystal resonator or clock to the XA and XB pins of the μPD72064. Note that a 32-MHz XA input is always required. For certain data transfer rates, a 19.2-MHz XB input is also required.

Table 11. System Clock Arrangement According to Data Transfer Rate

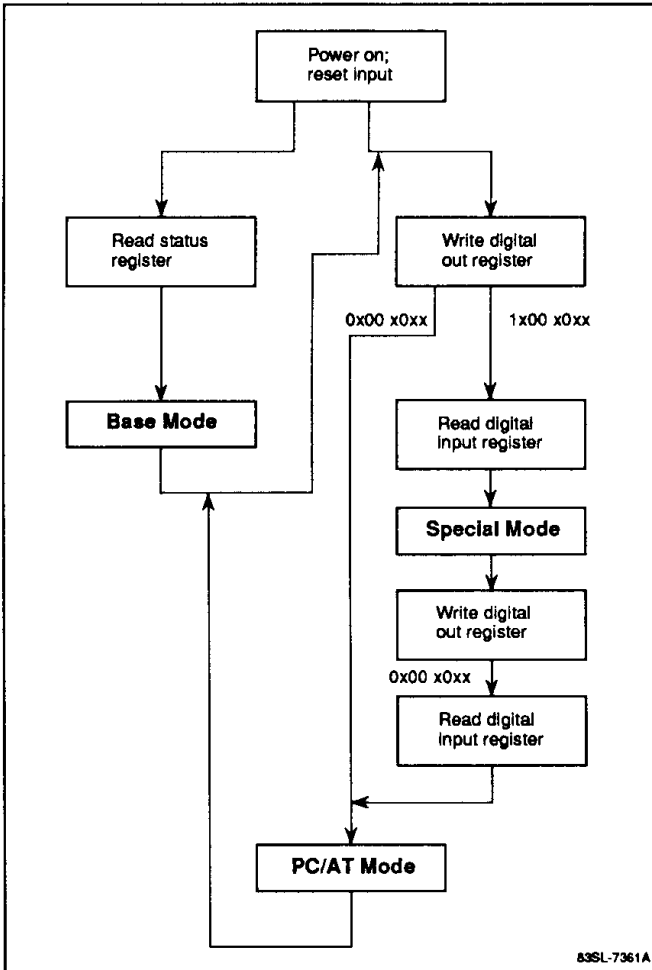
Connections to Pins	Data Transfer Rate, kb/s		
	500, 250	500, 300	300, 250
Crystal Resonator			
XA1, XA2	32 MHz	32 MHz	32 MHz
XB1, XB2	GND, Open	19.2 MHz	19.2 MHz
External Clock			
XA1 (*)	32 MHz	32 MHz	32 MHz
XB1 (*)	GND	19.2 MHz	19.2 MHz

* Leave pins XA2 and XB2 open

OPERATING MODES

Figure 2 shows the steps in setting the operating modes (base, special, and PC/AT) of the μPD72064.

Figure 2. Operating Modes Flowchart



COMMANDS

The μPD72064 FDC is capable of performing the 22 different commands listed in table 12. Each command is initiated by a multibyte transfer from the processor; after command execution, the result may be a multibyte transfer back to the processor. Because of this information interchange, it is convenient to consider each command as having three phases as follows.

Command FDC receives all information from the processor it needs to perform a particular operation.

Execution FDC performs the operation.

Result Status and other housekeeping information are made available to the processor

Most commands require nine command bytes and return seven bytes during the result phase. Table 13 is the FDC instruction set. Symbols in table 13 are explained in table 14.

Table 12. List of Commands

Command Name	Function
Read Commands	
READ DATA	Specifies a sector and transfers its data to the host.
READ DELETED DATA	
READ DIAGNOSTIC	Checks the track format.
READ ID	Reads a sector ID.
SCAN EQUAL	Compares each sector data with host data and detects a sector that satisfies the set condition.
SCAN LOW OR EQUAL	
SCAN HIGH OR EQUAL	
Write Commands	
WRITE DATA	Specifies a sector and transfers its data from the host.
WRITE DELETED DATA	
WRITE ID	Writes the format of a track.
Seek Commands	
RECALIBRATE	Moves the read/write head to the outermost track (track 0).
SEEK	Moves the read/write head to the specified cylinder.
Sense Commands	
SENSE INTERRUPT STATUS	Reads the interrupt factor (seek end/state change) in the μPD72064.
SENSE DEVICE STATUS	Reads the FDD status.
Initialize Command	
SPECIFY	Defines a μPD72064 operation mode.
Other Commands	
INVALID	Reports the issuance of an unnecessary command to the μPD72064.
VERSION	Identifies a B-type product.
Auxiliary Commands	
SET STANDBY	Drives the μPD72064 in the standby status.
RESET STANDBY	Releases the μPD72064 from the standby status.
SOFTWARE RESET	Initializes the μPD72064.
START CLOCK	Starts the clock generator operation.
SELECT TRACK NUMBER	Specifies the maximum number of recalibratable tracks (77/255)

Table 13. Instruction Set

Phase	Instruction Code								Remarks
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀	
Read Data									
Command (Write)	MT	MF	SK	0	0	1	1	0	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
					C				Sector ID information prior to command execution. The four bytes are compared with the header on the floppy disk.
					H				
					R				
					N				
					EOT				
					GPL				
					DTL				
Execution									Data transfer between FDD and main system.
Result (Read)					ST0				Status information after command execution.
					ST1				
					ST2				
					C				Sector ID information after command execution.
					H				
					R				
					N				
Read Deleted Data									
Command (Write)	MT	MF	SK	0	1	1	0	0	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
					C				Sector ID information prior to command execution. The four bytes are compared with the header on the floppy disk.
					H				
					R				
					N				
					EOT				
					GPL				
					DTL				
Execution									Data transfer between FDD and main system.
Result (Read)					ST0				Status information after command execution.
					ST1				
					ST2				
					C				Sector ID information after command execution.
					H				
					R				
					N				

Notes:

- (1) A₀ should equal 1 for all operations.
- (2) x = Don't care; usually set to 0.

Table 13. Instruction Set (cont)

Phase	Instruction Code								Remarks
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀	
Read Diagnostic									
Command (Write)	0	MF	SK	0	0	0	1	0	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
					C				Sector ID information prior to command execution.
					H				
					R				
					N				
					EOT				
					GPL				
					DTL				
Execution									Data transfer between FDD and main system. FDC reads all data fields from index hole to EOT.
Result (Read)					ST0				Status information after command execution.
					ST1				
					ST2				
					C				Sector ID information after command execution.
					H				
					R				
					N				
Read ID									
Command (Write)	0	MF	0	0	1	0	1	0	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
Execution									The first correct ID information on the cylinder is stored in the data register.
Result (Read)					ST0				Status information after command execution.
					ST1				
					ST2				
					C				Sector ID information read during execution phase from floppy disk.
					H				
					R				
					N				

Table 13. Instruction Set (cont)

Phase	Instruction Code								Remarks
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀	
Scan Equal									
Command (Write)	MT	MF	SK	1	0	0	0	1	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
					C				Sector ID information prior to command execution.
					H				
					R				
					N				
					EOT				
					GPL				
					STP				
	Execution								
Result (Read)					ST0				Status information after command execution.
					ST1				
					ST2				
					C				Sector ID information after command execution.
					H				
					R				
					N				
					EOT				
					GPL				
					STP				
Scan Low or Equal									
Command (Write)	MT	MF	SK	1	1	0	0	1	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
					C				Sector ID information prior to command execution.
					H				
					R				
					N				
					EOT				
					GPL				
					STP				
	Execution								
Result (Read)					ST0				Status information after command execution.
					ST1				
					ST2				
					C				Sector ID information after command execution.
					H				
					R				
					N				
					EOT				
					GPL				
					STP				

Table 13. Instruction Set (cont)

Phase	Instruction Code									Remarks
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀		
Scan High or Equal										
Command (Write)	MT	MF	SK	1	1	1	0	1		Command codes.
	X	X	X	X	X	HD	US ₁	US ₀		
					C					Sector ID information prior to command execution.
					H					
					R					
					N					
					EOT					
					GPL					
					STP					
Execution										Data compared between FDD and main system.
Result (Read)					ST0					Status information after command execution.
					ST1					
					ST2					
					C					Sector ID information after command execution.
					H					
					R					
					N					
Write Data										
Command (Write)	MT	MF	0	0	0	1	0	1		Command codes.
	X	X	X	X	X	HD	US ₁	US ₀		
					C					Sector ID information prior to command execution. The four bytes are compared with the header on the floppy disk.
					H					
					R					
					N					
					EOT					
					GPL					
					DTL					
Execution										Data transfer between FDD and main system.
Result (Read)					ST0					Status information after command execution.
					ST1					
					ST2					
					C					Sector ID information after command execution.
					H					
					R					
					N					

Table 13. Instruction Set (cont)

Phase	Instruction Code								Remarks
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀	
Write Deleted Data									
Command (Write)	MT	MF	0	0	1	0	0	1	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
					C				Sector ID information prior to command execution. The four bytes are compared with the header on the floppy disk.
					H				
					R				
					N				
					EOT				
					GPL				
					DTL				
Execution									Data transfer between FDD and main system.
Result (Read)					ST0				Status information after command execution.
					ST1				
					ST2				
					C				Sector ID information after command execution.
					H				
					R				
					N				
Write ID (Format Write)									
Command (Write)	0	MF	0	0	1	1	0	1	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
					N				Bytes/sector
					SC				Sectors/track
					GPL				Gap 3
					D				Filler byte
Execution									FDC formats an entire track.
Result (Read)					ST0				Status information after command execution.
					ST1				
					ST2				
					C				In this case, the ID information has no meaning
					H				
					R				
					N				
Recalibrate									
Command (Write)	0	0	0	0	0	1	1	1	Command codes.
	X	X	X	X	X	0	US ₁	US ₀	
Execution									Head retracted to track 0.

Table 13. Instruction Set (cont)

Phase	Instruction Code								Remarks
	D ₇	D ₆	D ₅	D ₄	D ₃	D ₂	D ₁	D ₀	
Seek									
Command (Write)	0	0	0	0	1	1	1	1	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
	NCN								
Execution									Head is positioned over proper cylinder on diskette.
Sense Interrupt Status									
Command (Write)	0	0	0	0	1	0	0	0	Command code.
Result (Read)	ST0								Status information about FDC at the end of seek operation.
	PCN								
Sense Device Status									
Command (Write)	0	0	0	0	0	1	0	0	Command codes.
	X	X	X	X	X	HD	US ₁	US ₀	
Result (Read)	ST3								Status information about FDD.
Specify									
Command (Write)	0	0	0	0	0	0	1	1	Command codes.
	SRT (D ₇ -D ₄)				HUT (D ₃ -D ₀)				
	HLT (D ₇ -D ₁)						ND		
Invalid									
Command (Write)	Invalid Codes								Invalid command codes.
Result (Read)	ST0								ST0 = 80H
Version									
Command (Write)	X	X	X	1	0	0	0	0	Command code.
Result (Read)	1	0	0	*1	0	0	0	0	*Indicates B-type product.
Set Standby									
Command (Write)	0	0	1	1	0	1	0	1	
Reset Standby									
Command (Write)	0	0	1	1	0	1	0	0	
Result (Read)	1	0	0	0	0	0	0	0	Invalid command.
Software Reset									
Command (Write)	0	0	1	1	0	1	1	0	
Start Clock									
Command (Write)	0	1	0	0	0	1	1	1	
Select Track Number									
Command (Write)	0	1	0	TR	1	1	1	1	
Result (Read)	1	0	0	0	0	0	0	0	Invalid command.

Table 14. Command Symbols

Symbol	Name	Description
A ₀	Address Line 0	Controls selection of main status register (A ₀ = 0) or data register (A ₀ = 1).
C	Cylinder Number	Current/selected cylinder (track) 0 through 76 of the medium.
D	Data	Data pattern that is going to be written into a sector during WRITE ID operation.
D ₇ -D ₀	Data Bus	8-bit data bus, where D ₇ stands for the most significant bit, and D ₀ stands for the least significant bit.
DTL	Data Length	When N is defined as 00, DTL stands for the data length that users are going to read out or write into the sector.
EOT	End of Track	Final sector number on a cylinder. During read or write operations, FDC will stop data transfer after a sector number equal to EOT.
GPL	Gap Length	Length of gap 3. During Read/Write commands, this value determines the number of bytes that VC0 sync will stay low after two CRC bytes. During format command, it determines the size of gap 3.
H	Head Address	Logical head number 0 or 1, as specified in ID field.
HD	Head	Physical head number 0 or 1. Controls the polarity of the SIDE pin. (H = HD in all command words.)
HLT	Head Load Time	Head load time in the FDD (2 to 254 ms in 2-ms increments).
HUT	Head Unload Time	Head unload time after a Read or Write operation has occurred (16 to 240 ms in 16-ms increments).
MF	FM or MFM Mode	If MF is low, FM mode is selected; if it is high, MFM mode is selected.
MT	Multitrack	If MT is high, a multitrack operation is performed. If MT = 1 after finishing read/write operation on side 0, the FDC will automatically start searching for sector 1 on side 1.
N	Number	Number of data bytes written in a sector.
NCN	New Cylinder Number	New cylinder number that is going to be reached as a result of the seek operation; desired position of head.
ND	Non-DMA Mode	Operation in the non-DMA mode.
PCN	Present Cylinder Number	Cylinder number at the completion of Sense Interrupt Status command (head position at present time).
R	Record	Sector number that will be read or written.
RW	Read/Write	Read (R) or Write (W) signal.
SC	Sector	Number of sectors per cylinder.
SK	Skip	Skip deleted data address mark.
SRT	Step Rate Time	Stepping rate for the FDD (1 to 16 ms in 1-ms increments). Stepping rate applies to all drives (FH = 1 ms, EH = 2 ms, etc.).
ST0-ST3	Status 0-3	ST0-ST3 stands for one of four registers that store the status information after a command has been executed. This information is available during the result phase after command execution. These registers should not be confused with the main status register (selected by A ₀ = 0). ST0-ST3 may be read only after a command has been executed and contains information relevant to that particular command.
STP		During a scan operation, if STP = 1, the data in contiguous sectors is compared byte by byte with data sent from the processor (or DMA); if STP = 2, then alternate sectors are read and compared.
US ₀ , US ₁	Unit Select	Selected drive number 0 or -3.

ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings

T_A = +25°C

Supply voltage, V _{DD}	-0.5 to +7.0 V
Voltage on any pin (except V _{DD})	-0.5 to V _{DD} + 0.5
Operating temperature, T _{OPT}	-10 to +70°C
Storage temperature, T _{STG}	-65 to 150°C

Capacitance

T_A = +25°C; V_{DD} = 0 V; f = 1 MHz

Parameter	Symbol	Min	Max	Unit	Conditions
Clock capacitance	C _φ		20	pF	Unmeasured pins returned to 0 V.
Input capacitance	C _{IN}		20	pF	
Output capacitance	C _{OUT}		20	pF	

Oscillator Specifications

T_A = -10 to +70°C; V_{DD} = +5 V ±10%; see figures 3, 4 and 5.

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Crystal Resonator Source						
Oscillator stabilization time (Note 1)	t _{KS}			10	ms	
External Clock, Direct Input						
Low-level input voltage	V _{IL}	-0.5		0.2 V _{DD}	V	Pins XA1, XB1
High-level input voltage	V _{IH}	0.8 V _{DD}		V _{DD} + 0.5	V	
Clock cycle	t _{CYA}		31.25		ns	Pin XA1
	t _{CYB}		52.08		ns	Pin XB1
Permissible clock cycle error from typical value (Note 2)				±0.5	%	Pins XA1, XB1
Clock high-level width	t _{KKH}		7.0		ns	Pin XA1
			15.0		ns	Pin XB1
Clock low-level width	t _{KKL}		7.0		ns	Pin XA1
			15.0		ns	Pin XB1
Clock rise time	t _{KR}			5.0	ns	
Clock fall time	t _{KF}			5.0	ns	
External Clock, Capacitor-Coupled Input						
Clock input amplitude	V _{KP-P}	2.0		V _{DD}	V	Pins XA1, XB1
Clock cycle	t _{CYA}		31.25		ns	Pin XA1
	t _{CYB}		52.08		ns	Pin XB1
Permissible clock cycle error from typical value (Note 2)				±0.5	%	Pins XA1, XB1
Duty cycle, high-level			40	60	%	

Notes:

- (1) Oscillator stabilization time should also be taken as the wait time between the issuance of START CLOCK and RESET STANDBY commands.
- (2) Clock cycle error affects DPLL performance.

Figure 3. Recommended External Clock Circuits

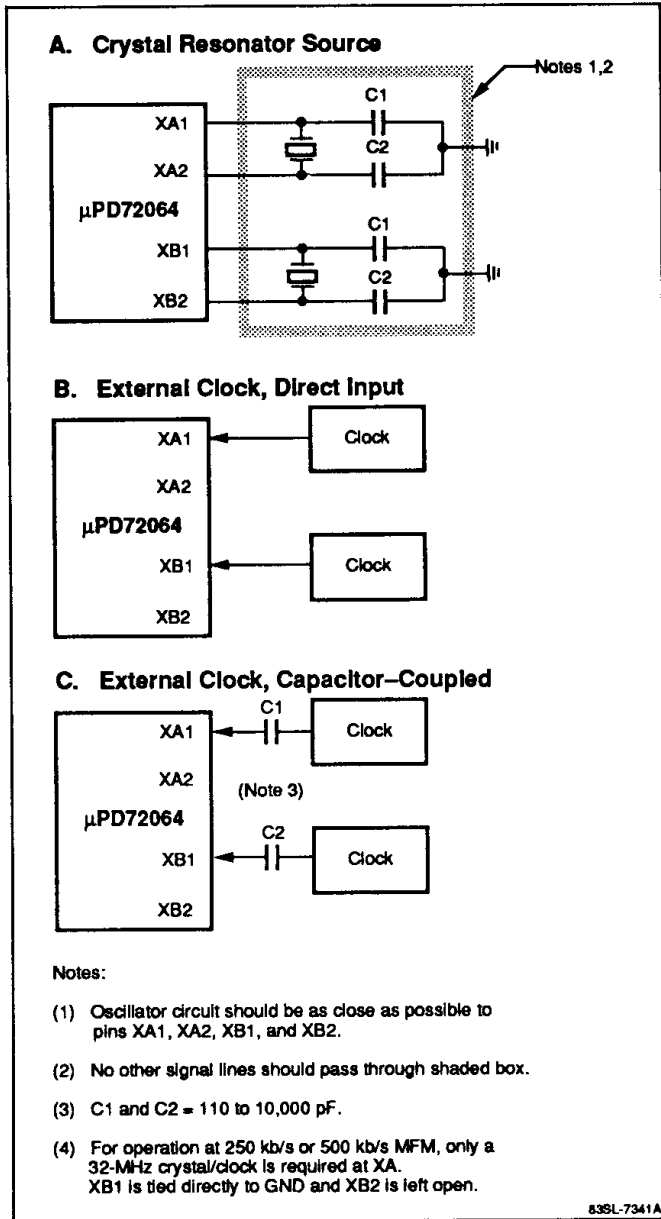


Figure 4. External Clock Waveform

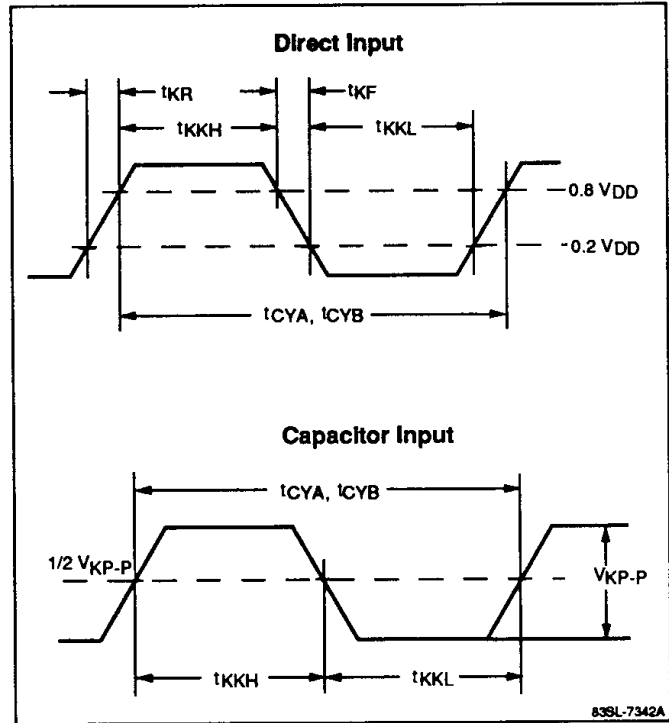
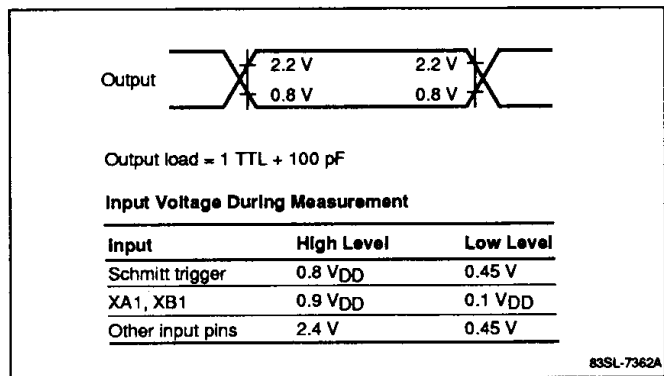


Figure 5. Voltage Thresholds for Timing Measurements



DC Characteristics

$T_A = -10$ to $+70^\circ\text{C}$; $V_{DD} = +5\text{V} \pm 10\%$

Parameter	Symbol	Pin Groups	Min	Max	Unit	Conditions
Low-level input voltage	V_{IL}	2	-0.5	0.8	V	
	V_{IL1}	1	-0.5	$0.2 V_{DD}$	V	
High-level input voltage	V_{IH}	2	2.2	$V_{DD} + 0.5$	V	
	V_{IH1}	1	$0.8 V_{DD}$	$V_{DD} + 0.5$	V	
Low-level output voltage	V_{OL}	4		0.45	V	$I_{OL} = 12\text{ mA}$
	V_{OL1}	3		0.45	V	$I_{OL} = 48\text{ mA}$
High-level output voltage	V_{OH}	4	$0.7 V_{DD}$	V_{DD}	V	$I_{OH} = -200\ \mu\text{A}$
Low-level input leakage current	I_{LIL}	1, 2		-10	μA	$V_{IN} = 0\text{ V}$
High-level input leakage current	I_{LIH}	1, 2		+10	μA	$V_{IN} = V_{DD}$
Low-level output leakage current	I_{LOL}	4		-10	μA	$V_{OUT} = +0.45\text{ V}$
	I_{LOL1}	3		-100	μA	
High-level output leakage current	I_{LOH}	4		+10	μA	$V_{OUT} = V_{DD}$
	I_{LOH1}	3		+100	μA	
V_{DD} supply current	I_{DD}			60	mA	
Standby current	I_{DD1}			100	μA	

Pin Groups:

- (1) Schmitt-trigger inputs: DKCG, INDEX, RDATA, TRK0, WPRT.
- (2) Other inputs: A0, ACCR, ACDR, CS, D₀-D₇, DKCGEN, DMAAK, DRVTYP, PCSVL, RD, RESET, TC, WR; excludes XA1, XA2, XB1, XB2.
- (3) Open-drain outputs: DIR, DS1, DS2, SIDE, STEP, WDATA, WE.
Disk drive outputs: DEN/LCT, EMI/DS3, EM2/DS4, HDL D.
- (4) Other outputs: D₀-D₇, DMARQ, INT.

AC Characteristics 1; 500 kb/s

$T_A = -10$ to $+70^\circ\text{C}$; $V_{DD} = +5\text{ V} \pm 10\%$;

MFM data transfer rate = 500 kb/s; $t_{CYA} = 31.25\text{ ns}$ (32 MHz at XA1 pin)

Parameter	Figure	Symbol	Min	Typ	Max	Unit	Conditions
Main System Side							
A0, $\overline{\text{ACCR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ setup time to $\overline{\text{RD}}$	6	t_{AR}	0			ns	
A0, $\overline{\text{ACCR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ hold time from $\overline{\text{RD}}$	6	t_{RA}	0			ns	
$\overline{\text{RD}}$ pulse width	6	t_{RR}	90			ns	
Data access time from $\overline{\text{RD}} \downarrow$	6	t_{RD}			90	ns	
Data float delay time from $\overline{\text{RD}} \uparrow$	6	t_{DF}	10		85	ns	
INT delay time from $\overline{\text{RD}} \uparrow$	6	t_{RI}			200	ns	When data is transferred in non-DMA mode.
A0, $\overline{\text{ACCR}}$, $\overline{\text{ACDR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ setup time to $\overline{\text{WR}}$	7	t_{AW}	0			ns	
A0, $\overline{\text{ACCR}}$, $\overline{\text{ACDR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ hold time from $\overline{\text{WR}}$	7	t_{WA}	0			ns	
$\overline{\text{WR}}$ pulse width	7	t_{WW}	60			ns	
Data setup time to $\overline{\text{WR}}$	7	t_{DW}	80			ns	
Data hold time from $\overline{\text{WR}}$	7	t_{WD}	0			ns	
INT delay time from $\overline{\text{WR}} \uparrow$	7	t_{WI}			200	ns	When data is transferred in non-DMA mode.
DMARQ cycle time	8	t_{MCY}	13			μs	
$\overline{\text{DMAAK}} \downarrow$ response time from DMARQ \uparrow	8	t_{MA}	0			ns	
DMARQ delay time from $\overline{\text{DMAAK}} \downarrow$	8	t_{AM}			140	ns	
$\overline{\text{DMAAK}}$ pulse width	8	t_{AA}	90			ns	
$\overline{\text{RD}} \downarrow$ response time from DMARQ \uparrow	8	t_{MR}	0			ns	
$\overline{\text{WR}} \downarrow$ response time from DMARQ \uparrow	8	t_{MW}	0			ns	
$\overline{\text{WR}}/\overline{\text{RD}}$ response time from DMARQ \uparrow	8	t_{MRW}			12	μs	
TC pulse width	8	t_{TC}	60			ns	
Clock hold time on standby	9	t_{WC}	4			μs	
Clock setup time after standby release	9	t_{CW}	2			μs	
START CLOCK command write setup time to RESET STANDBY command write	9	t_{WS}	2			μs	
INT response time from DMARQ \downarrow	10	t_{MI}	7.5		9.6	μs	
$\overline{\text{DMAAK}}$ signal invalid from INT \uparrow	10	t_{IA}			125	ns	
RESET pulse width	11	t_{RST}	250			μs	

AC Characteristics 1; 500 kb/s (cont)

Parameter	Figure	Symbol	Min	Typ	Max	Unit	Conditions
Drive Side							
RDATA low-level width	12	t _{RDD}	40			ns	
WDATA low-level width	12	t _{WDD}		250		ns	
DS1-DS4 setup time to DIR (Note 3)	13	t _{DSD}	12			μs	Note 1
DIR setup time to STEP	13	t _{DST}	1			μs	
DS1-DS4 hold time from STEP (Note 3)	13	t _{STU}	5			μs	
STEP low-level width	13	t _{STP}	6	7	8	μs	
DS1-DS4 hold time from DIR (Notes 2, 3)	13	t _{DDS}	15			μs	
DIR hold time from STEP	13	t _{STD}	24			μs	
STEP cycle time	13	t _{SC}	33			μs	
INDEX low-level width	14	t _{IDX}	500			ns	

Notes:

- (1) The minimum value for drive-side parameters is 50 ns less than the value expressed in μs. For example, 12 μs is actually 11.950 μs.
- (2) While the unit under test is performing a seek operation, the SENSE DEVICE STATUS command is being executed for the other devices.
- (3) Except in PC/AT mode.
- (4) See figure 5 for timing measurement voltage thresholds.

AC Characteristics 2; 250 kb/s

$T_A = -10$ to $+70^\circ\text{C}$; $V_{DD} = +5\text{V} \pm 10\%$;

MFM data transfer rate = 250 kb/s; $t_{CYA} = 31.25$ ns (32 MHz at XA1 pin)

Parameter	Figure	Symbol	Min	Typ	Max	Unit	Conditions
Main System Side							
A0, $\overline{\text{ACCR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ setup time to $\overline{\text{RD}}$	6	t_{AR}	0			ns	
A0, $\overline{\text{ACCR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ hold time from $\overline{\text{RD}}$	6	t_{RA}	0			ns	
$\overline{\text{RD}}$ pulse width	6	t_{RR}	90			ns	
Data access time from $\overline{\text{RD}} \downarrow$	6	t_{RD}			90	ns	
Data float delay time from $\overline{\text{RD}} \uparrow$	6	t_{DF}	10		85	ns	
INT delay time from $\overline{\text{RD}} \uparrow$	6	t_{RI}			200	ns	When data is transferred in non-DMA mode.
A0, $\overline{\text{ACCR}}$, $\overline{\text{ACDR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ setup time to $\overline{\text{WR}}$	7	t_{AW}	0			ns	
A0, $\overline{\text{ACCR}}$, $\overline{\text{ACDR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ hold time from $\overline{\text{WR}}$	7	t_{WA}	0			ns	
$\overline{\text{WR}}$ pulse width	7	t_{WW}	60			ns	
Data setup time to $\overline{\text{WR}}$	7	t_{DW}	80			ns	
Data hold time from $\overline{\text{WR}}$	7	t_{WD}	0			ns	
INT delay time from $\overline{\text{WR}} \uparrow$	7	t_{WI}			200	ns	When data is transferred in non-DMA mode.
DMARQ cycle time	8	t_{MCY}	26			μs	
$\overline{\text{DMAAK}} \downarrow$ response time from DMARQ \uparrow	8	t_{MA}	0			ns	
DMARQ delay time from $\overline{\text{DMAAK}} \downarrow$	8	t_{AM}			140	ns	
$\overline{\text{DMAAK}}$ pulse width	8	t_{AA}	90			ns	
$\overline{\text{RD}} \downarrow$ response time from DMARQ \uparrow	8	t_{MR}	0			ns	
$\overline{\text{WR}} \downarrow$ response time from DMARQ \uparrow	8	t_{MW}	0			ns	
$\overline{\text{WR}}/\overline{\text{RD}}$ response time from DMARQ \uparrow	8	t_{MRW}			24	μs	
TC pulse width	8	t_{TC}	60			ns	
Clock hold time on standby	9	t_{WC}	8			μs	
Clock setup time after standby release	9	t_{CW}	4			μs	
START CLOCK command write setup time to RESET STANDBY command write	9	t_{WS}	4			μs	
INT response time from DMARQ \downarrow	10	t_{MI}	15		19.2	μs	
$\overline{\text{DMAAK}}$ signal invalid from INT \uparrow	10	t_{IA}			250	ns	
RESET pulse width	11	t_{RST}	250			μs	

AC Characteristics 2; 250 kb/s (cont)

Parameter	Figure	Symbol	Min	Typ	Max	Unit	Conditions
Drive Side							
RDATA low-level width	12	t _{RDD}	40			ns	
WDATA low-level width	12	t _{WDD}		500		ns	
DS1-DS4 setup time to DIR (Note 3)	13	t _{DSD}	24			μs	Note 1
DIR setup time to STEP	13	t _{DST}	2			μs	
DS1-DS4 hold time from STEP (Note 3)	13	t _{STU}	10			μs	
STEP low-level width	13	t _{STP}	12	14	16	μs	
DS1-DS4 hold time from DIR (Notes 2, 3)	13	t _{DDS}	30			μs	
DIR hold time from STEP	13	t _{STD}	48			μs	
STEP cycle time	13	t _{SC}	66			μs	
INDEX low-level width	14	t _{IDX}	1000			ns	

Notes:

- (1) The minimum value for drive-side parameters is 50 ns less than the value expressed in μs. For example, 12 μs is actually 11.950 μs.
- (2) While the unit under test is performing a seek operation, the SENSE DEVICE STATUS command is being executed for the other devices.
- (3) Except in PC/AT mode.
- (4) See figure 5 for timing measurement voltage thresholds.

AC Characteristics 3; 300 kb/s

$T_A = -10$ to $+70^\circ\text{C}$; $V_{DD} = +5\text{ V} \pm 10\%$;

MFM data transfer rate = 300 kb/s; $t_{CYA} = 31.25\text{ ns}$ (32 MHz at XA1 pin)

Parameter	Figure	Symbol	Min	Typ	Max	Unit	Conditions
Main System Side							
AO, $\overline{\text{ACCR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ setup time to $\overline{\text{RD}}$	6	t_{AR}	0			ns	
AO, $\overline{\text{ACCR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ hold time from $\overline{\text{RD}}$	6	t_{RA}	0			ns	
$\overline{\text{RD}}$ pulse width	6	t_{RR}	90			ns	
Data access time from $\overline{\text{RD}} \downarrow$	6	t_{RD}			90	ns	
Data float delay time from $\overline{\text{RD}} \uparrow$	6	t_{DF}	10		85	ns	
INT delay time from $\overline{\text{RD}} \uparrow$	6	t_{RI}			200	ns	When data is transferred in non-DMA mode.
AO, $\overline{\text{ACCR}}$, $\overline{\text{ACDR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ setup time to $\overline{\text{WR}}$	7	t_{AW}	0			ns	
AO, $\overline{\text{ACCR}}$, $\overline{\text{ACDR}}$, $\overline{\text{CS}}$, $\overline{\text{DMAAK}}$ hold time from $\overline{\text{WR}}$	7	t_{WA}	0			ns	
$\overline{\text{WR}}$ pulse width	7	t_{WW}	60			ns	
Data setup time to $\overline{\text{WR}}$	7	t_{DW}	80			ns	
Data hold time from $\overline{\text{WR}}$	7	t_{WD}	0			ns	
INT delay time from $\overline{\text{WR}} \uparrow$	7	t_{WI}			200	ns	When data is transferred in non-DMA mode.
DMARQ cycle time	8	t_{MCY}	21.7			μs	
$\overline{\text{DMAAK}} \downarrow$ response time from DMARQ \uparrow	8	t_{MA}	0			ns	
DMARQ delay time from $\overline{\text{DMAAK}} \downarrow$	8	t_{AM}			140	ns	
$\overline{\text{DMAAK}}$ pulse width	8	t_{AA}	90			ns	
$\overline{\text{RD}} \downarrow$ response time from DMARQ \uparrow	8	t_{MR}	0			ns	
$\overline{\text{WR}} \downarrow$ response time from DMARQ \uparrow	8	t_{MW}	0			ns	
$\overline{\text{WR}}/\overline{\text{RD}}$ response time from DMARQ \uparrow	8	t_{MRW}			20	μs	
TC pulse width	8	t_{TC}	60			ns	
Clock hold time on standby	9	t_{WC}	6.7			μs	
Clock setup time after standby release	9	t_{CW}	3.3			μs	
START CLOCK command write setup time to RESET STANDBY command write	9	t_{WS}	3.3			μs	
INT response time from DMARQ \downarrow	10	t_{MI}	12.5		16.0	μs	
$\overline{\text{DMAAK}}$ signal invalid from INT \uparrow	10	t_{IA}			208.3	ns	
RESET pulse width	11	t_{RST}	250			μs	

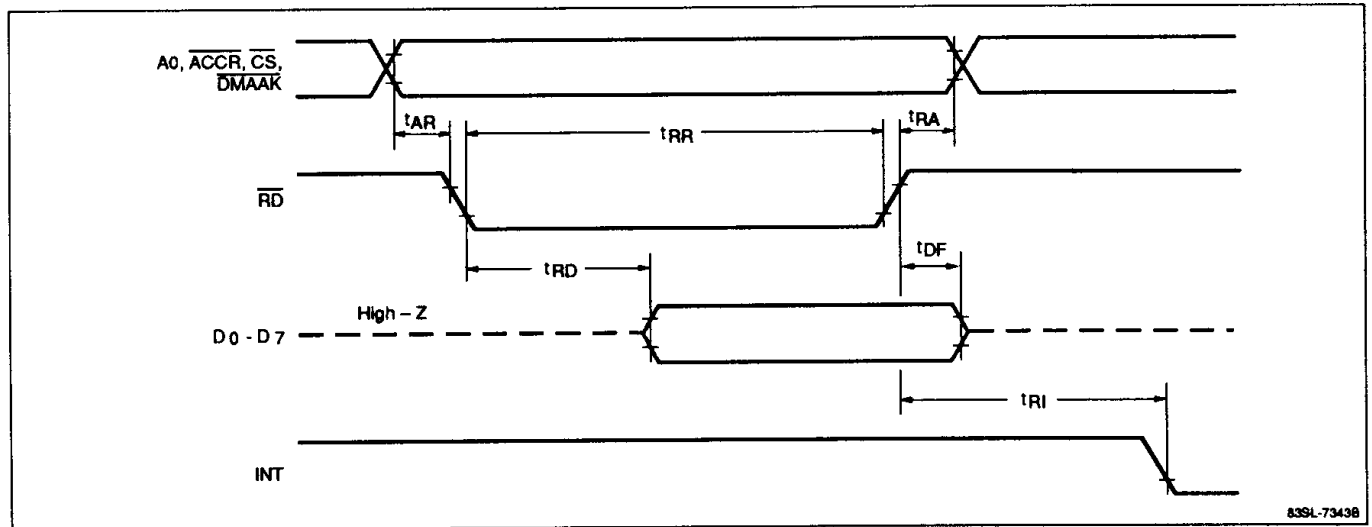
AC Characteristics 3; 300 kb/s (cont)

Parameter	Figure	Symbol	Min	Typ	Max	Unit	Conditions
Drive Side							
RDATA low-level width	12	t _{RDD}	40			ns	
WDATA low-level width	12	t _{WDD}		416.7		ns	
DS1-DS4 setup time to $\overline{\text{DIR}}$ (Note 3)	13	t _{DSD}	20			μs	Note 1
$\overline{\text{DIR}}$ setup time to STEP	13	t _{DST}	1.7			μs	
DS1-DS4 hold time from $\overline{\text{STEP}}$ (Note 3)	13	t _{STU}	8.3			μs	
STEP low-level width	13	t _{STP}	10	11.7	13.3	μs	
DS1-DS4 hold time from $\overline{\text{DIR}}$ (Notes 2, 3)	13	t _{DDS}	25			μs	
$\overline{\text{DIR}}$ hold time from STEP	13	t _{STD}	40			μs	
STEP cycle time	13	t _{SC}	55			μs	
INDEX low-level width	14	t _{IDX}	833.3			ns	

Notes:

- (1) The minimum value for drive-side parameters is 50 ns less than the value expressed in μs. For example, 12 μs is actually 11.950 μs.
- (2) While the unit under test is performing a seek operation, the SENSE DEVICE STATUS command is being executed for the other devices.
- (3) Except in PC/AT mode.
- (4) See figure 5 for timing measurement voltage thresholds.

Figure 6. Read Operation



83SL-7343B

Figure 7. Write Operation

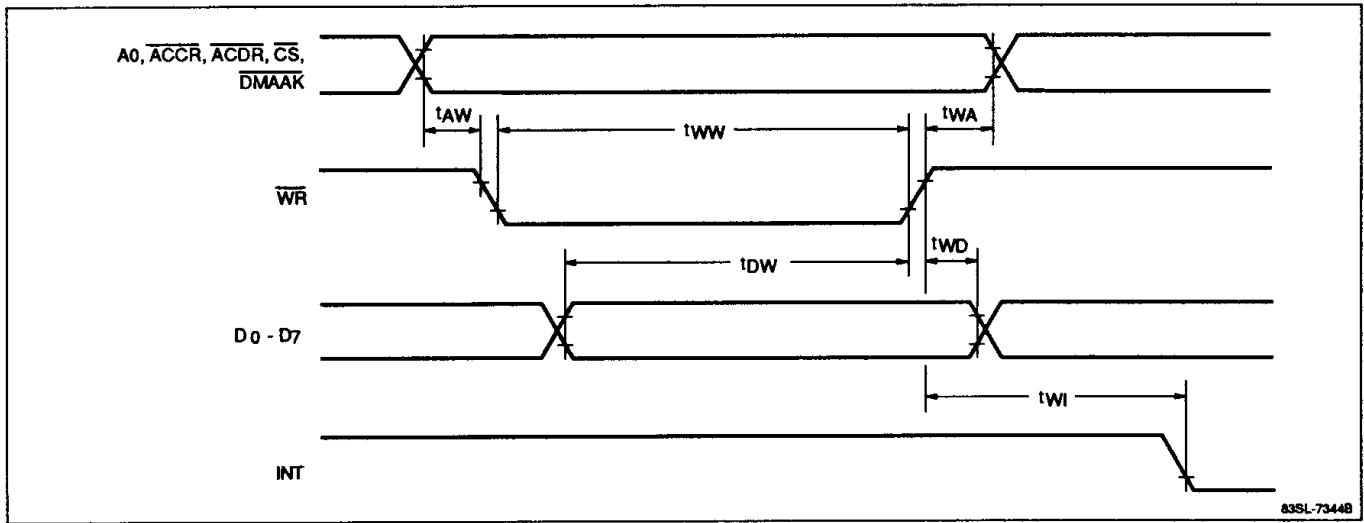


Figure 8. DMA Operation

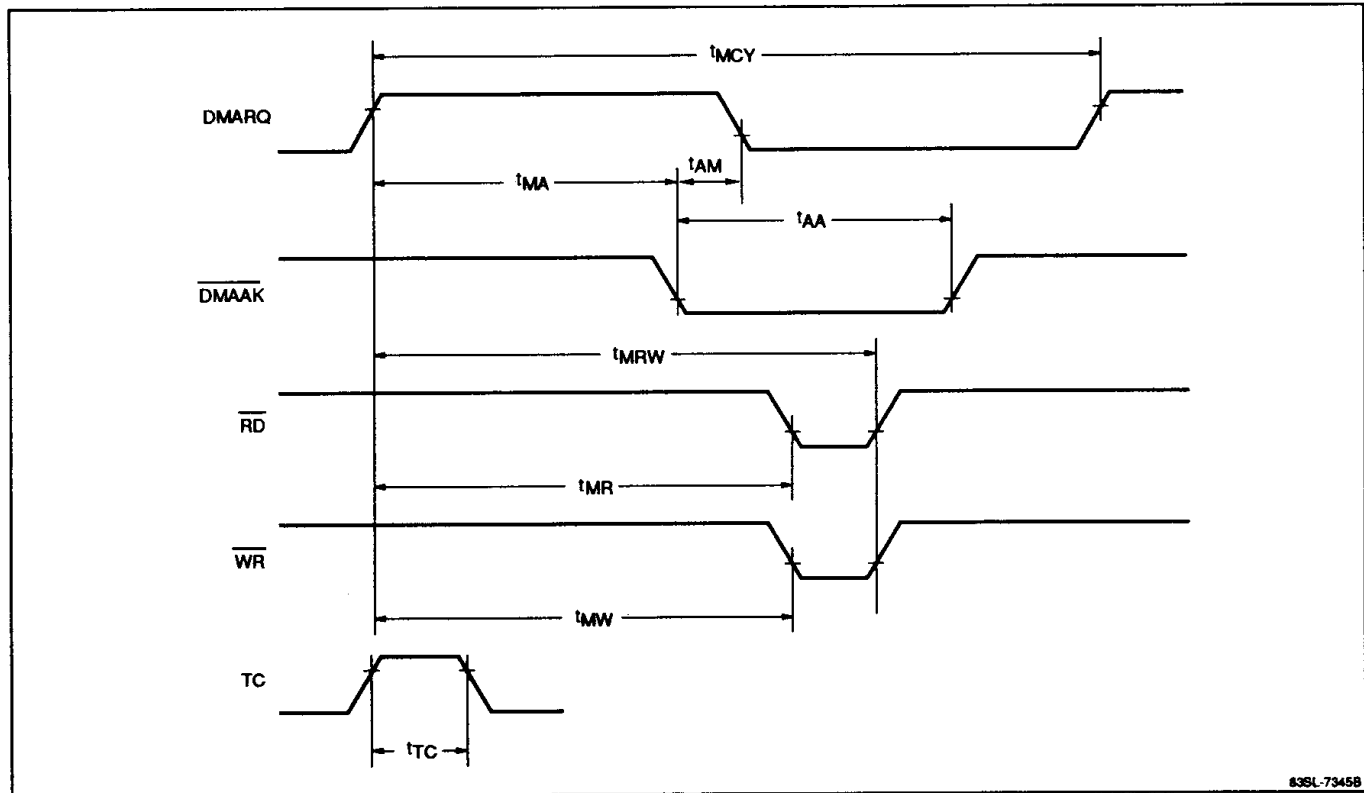


Figure 9. Standby Operation

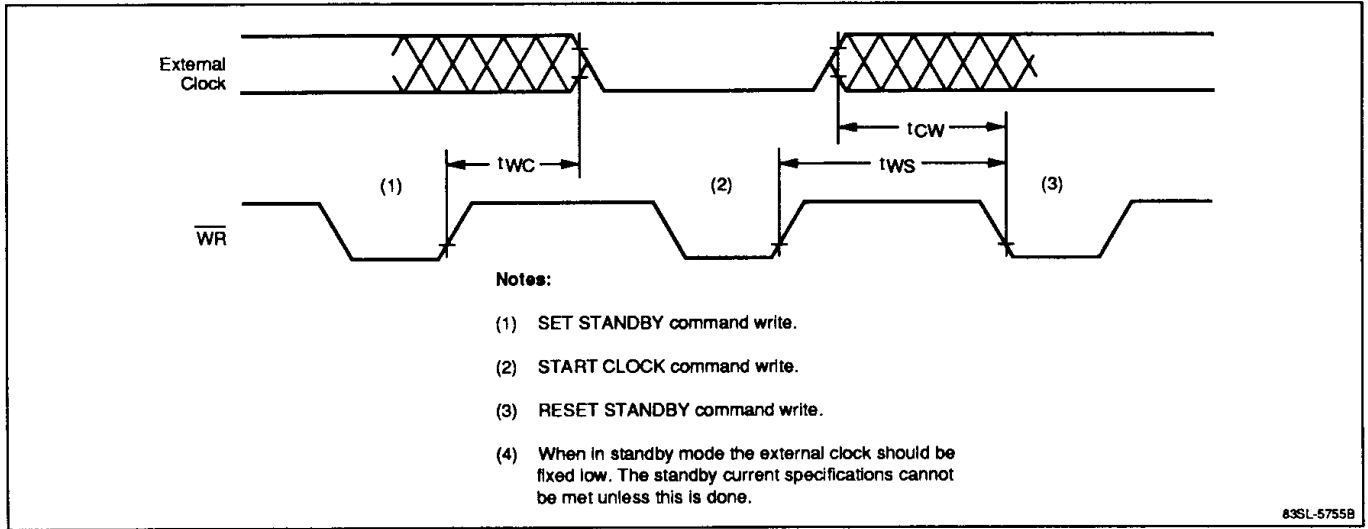


Figure 10. Operation in Case of Overrun

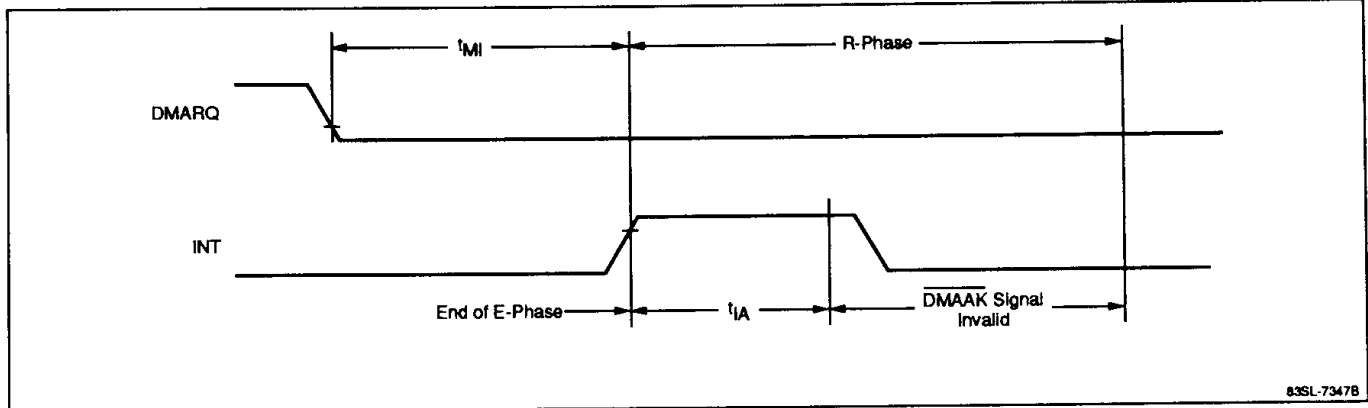


Figure 11. RESET Waveform

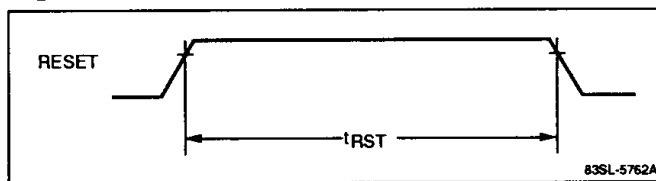


Figure 12. \overline{RDATA} and \overline{WDATA} Waveforms

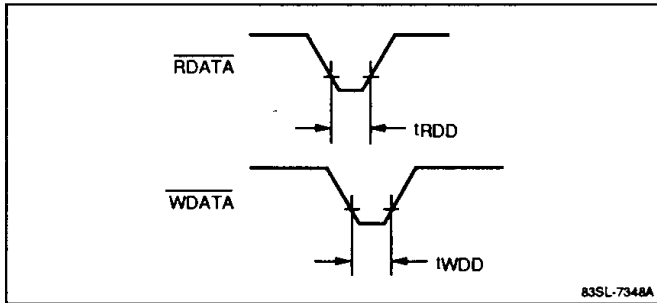


Figure 13. Seek Operation

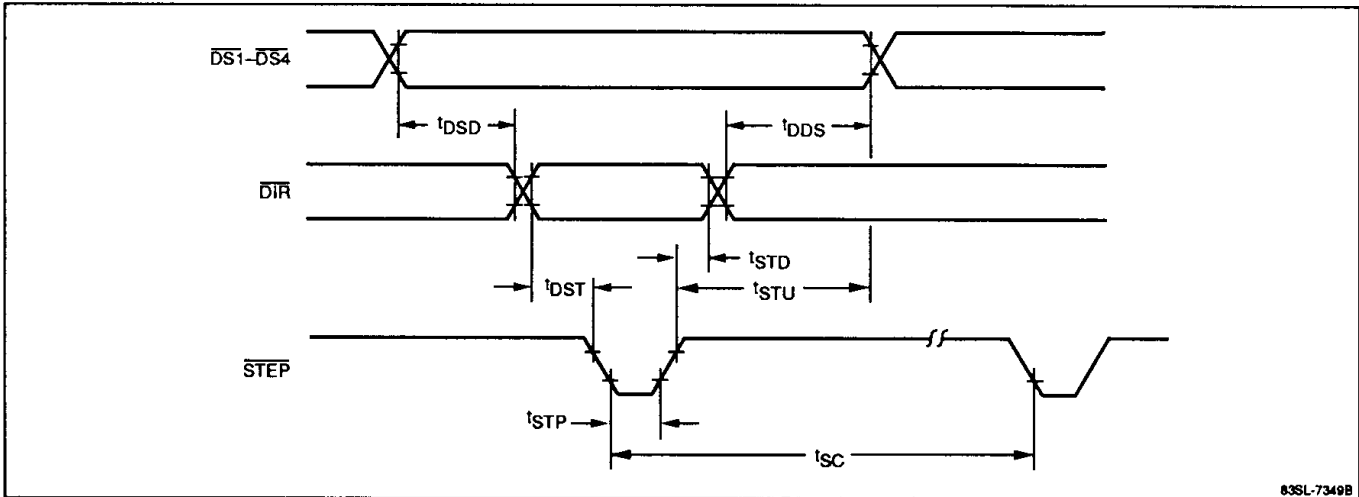
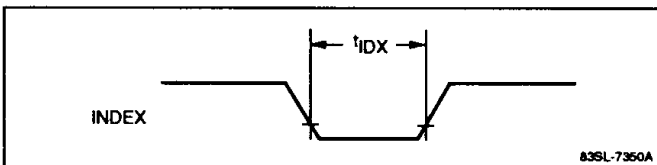


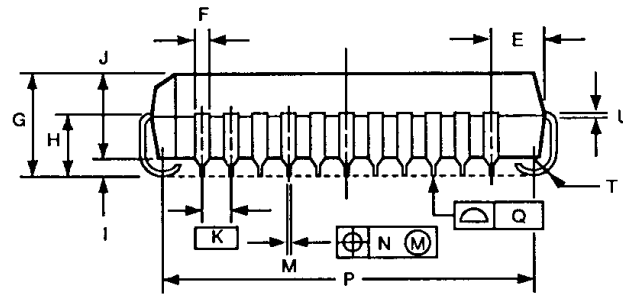
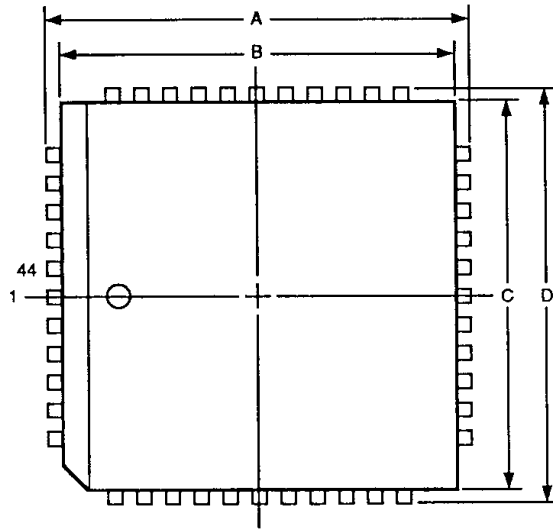
Figure 14. INDEX Waveform



PACKAGE DRAWINGS

44-Pin PLCC

Item	Millimeters	Inches
A	17.5 ±0.2	.689 ±.008
B	16.58	.653
C	16.58	.653
D	17.5 ±0.2	.689 ±.008
E	1.94 ±0.15	.076 ±.006
F	0.6	.024
G	4.4 ±0.2	.173 ±.008
H	2.8 ±0.2	.110 ±.008
I	0.9 min	.035 min
J	3.4	.134
K	1.27 (TP)	.050 (TP)
M	0.40 ±0.10	.016 ±.004
N	0.12	.005
P	15.50 ±0.20	.610 ±.008
Q	0.15	.006
T	0.8 radius	.031 radius
U	0.20 ^{+0.10} / _{-0.05}	.008 ^{+0.004} / _{-.002}

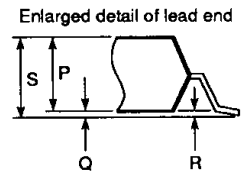
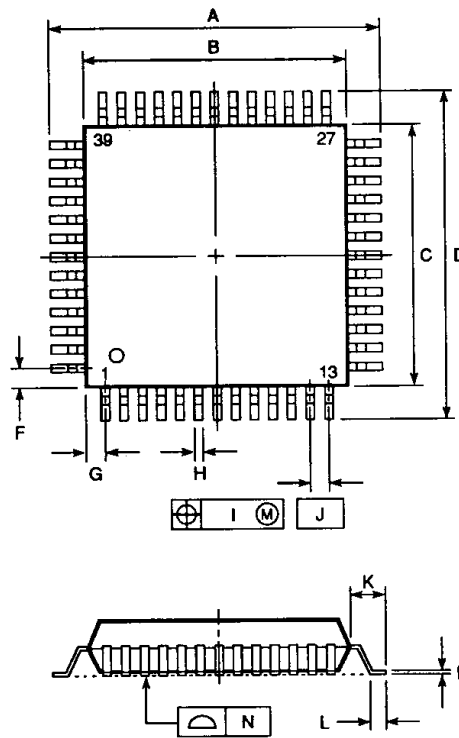


P44L-50A1-1

3/90 83YL-5804B

52-Pin Plastic QFP

Item	Millimeters	Inches
A	17.6 ± 0.4	.693 ± .016
B	14.0 ± 0.2	.551 ^{+ .009} _{-.008}
C	14.0 ± 0.2	.551 ^{+ .009} _{-.008}
D	17.6 ± 0.4	.693 ± .016
F	1.0	.039
G	1.0	.039
H	0.40 ± 0.10	.016 ^{+ .004} _{-.005}
I	0.20	.008
J	1.0 (TP)	.039 (TP)
K	1.8 ± 0.2	.071 ^{+ .008} _{-.009}
L	0.8 ± 0.2	.031 ^{+ .009} _{-.008}
M	0.15 ^{+ 0.10} _{-0.05}	.006 ^{+ .004} _{-.003}
N	0.15	.006
P	2.7	.106
Q	0.1 ± 0.1	.004 ± .004
R	0.1 ± 0.1	.004 ± .004
S	3.0 max	.119 max



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